

# Dual N-Channel 60 V (D-S) 175 °C MOSFET

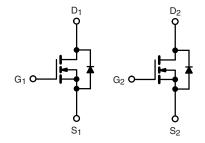
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.028			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.030			
I <sub>D</sub> (A) per leg	7			
Configuration	Dual			

# SO-8 Dual $\begin{array}{c} D_2 \\ D_2 \\ D_1 \\ 7 \\ 8 \\ \end{array}$ $\begin{array}{c} D_2 \\ 5 \\ \end{array}$ $\begin{array}{c} D_3 \\ G_2 \\ \end{array}$ $\begin{array}{c} 3 \\ G_2 \\ \end{array}$ $\begin{array}{c} G_2 \\ \end{array}$ $\begin{array}{c} Top \ View \\ \end{array}$

#### **FEATURES**

- TrenchFET® power MOSFET
- 100 % R<sub>q</sub> and UIS tested





N-Channel MOSFET N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	(T <sub>C</sub> = 25 °C, unles	s otherwise noted	)		
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V <sub>DS</sub>	60	V	
Gate-Source Voltage		$V_{GS}$	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C	1	7		
	T <sub>C</sub> = 125 °C	- I <sub>D</sub>	4		
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	3.6	Α	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	28		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	18		
Single Pulse Avalanche Energy	L = 0.1 IIII	E <sub>AS</sub>	16.2	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	р	4	W	
	T <sub>C</sub> = 125 °C	$P_{D}$	1.3	VV	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount <sup>c</sup> R <sub>thJA</sub>		110	°C/W	
Junction-to-Foot (Drain)		$R_{thJF}$	34	C/ VV	

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- c. When mounted on 1" square PCB (FR4 material).



PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static	•						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60	-	-	.,
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$		1.5	2.0	2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 60 V	=	-	1	μΑ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$	-	-	50	
		$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$	-	-	150	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	20	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 4.5 A-	-	0.028	-	Ω
Drain-Source On-State Resistance a	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 4.5 A, T <sub>J</sub> = 125 °C	-	0.066	-	
Drain Course on Clare Hooletanes	1 103(011)	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 4.5 A, T <sub>J</sub> = 175 °C	-	0.081	-	
	V <sub>GS</sub> = 4.5 V I <sub>D</sub> = 4 A-	-	0.030	-			
Forward Transconductance f	9fs	$V_{DS} = 15 \text{ V}, I_D = 4.5 \text{ A}$		-	15	_	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			-	600	750	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 25 V, f = 1 MHz	-	110	140	pF
Reverse Transfer Capacitance	C <sub>rss</sub>	1		-	50	62	
Total Gate Charge <sup>c</sup>	Qg			-	11.7	18	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 30 \text{ V}, I_{D} = 5.3 \text{ A}$	-	1.8	2.7	nC
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$	1		-	2.8	4.2	
Gate Resistance	$R_g$	f = 1 MHz		1.3	-	6	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>				7	11	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V, } R_L = 6.8 \Omega$ $I_D \cong 4.4 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 1 \Omega$		-	3.3	5	- ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	22.4	33.5	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	2.1	3.2	
Source-Drain Diode Ratings and Chara	acteristics b	•					
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	28	Α
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 2 A, V <sub>GS</sub> = 0 V		_	0.75	1.1	V

#### Notes

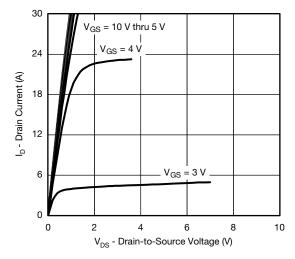
- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

服务热线:400-655-8788

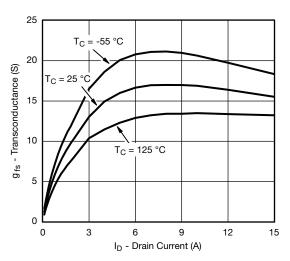
2



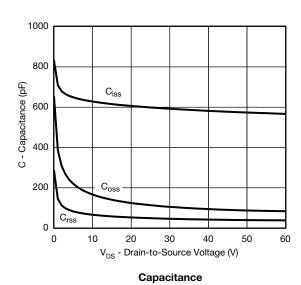
## **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



#### **Output Characteristics**

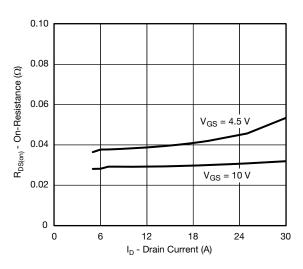


Transconductance

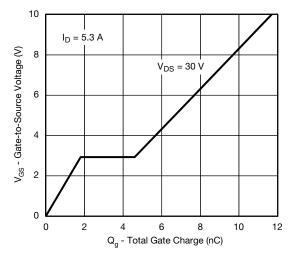


30
24
(V) traund 12  $T_{C} = 25 \, ^{\circ}C$   $T_{C} = 125 \, ^{\circ}C$   $T_{C} = -55 \, ^{\circ}C$ 

**Transfer Characteristics** 



On-Resistance vs. Drain Current



**Gate Charge** 

100

10

0.1

0.01

0.001

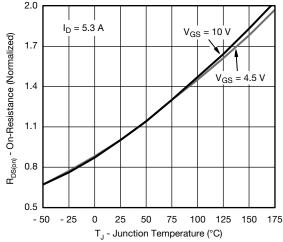
0

0.2

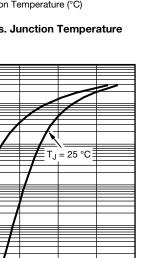
I<sub>S</sub> - Source Current (A)



## **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



On-Resistance vs. Junction Temperature

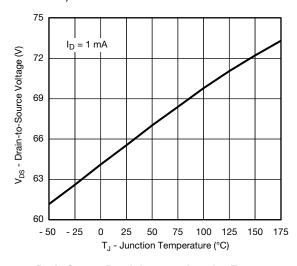


V<sub>SD</sub> - Source-to-Drain Voltage (V) **Source Drain Diode Forward Voltage** 

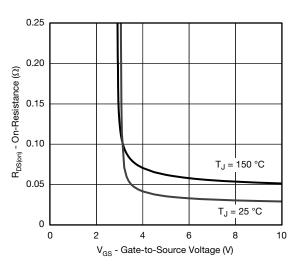
0.6

8.0

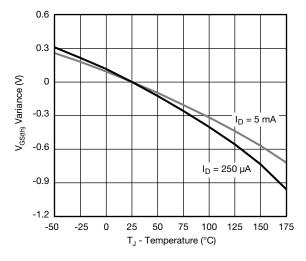
1.0



**Drain Source Breakdown vs. Junction Temperature** 



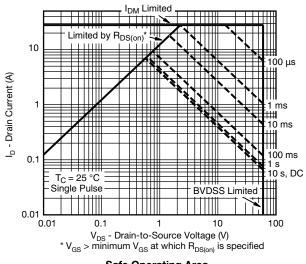
On-Resistance vs. Gate-to-Source Voltage



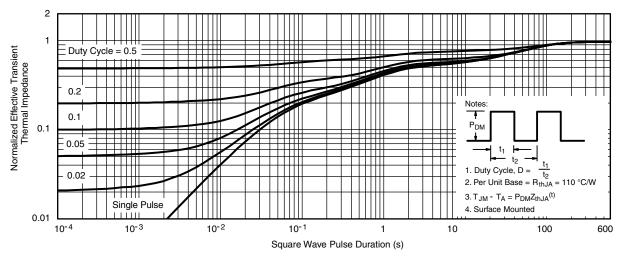
**Threshold Voltage** 



## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



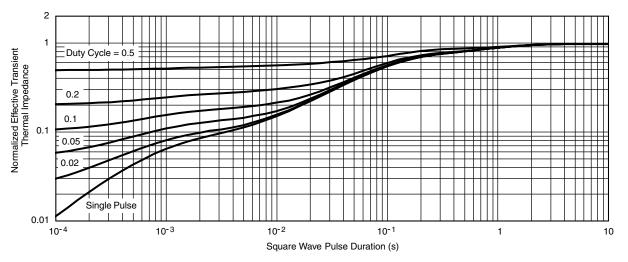
**Safe Operating Area** 



Normalized Thermal Transient Impedance, Junction-to-Ambient



## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot

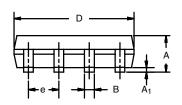
服务热线:400-655-8788

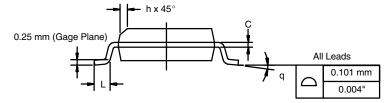
6



**SOIC (NARROW): 8-LEAD**JEDEC Part Number: MS-012





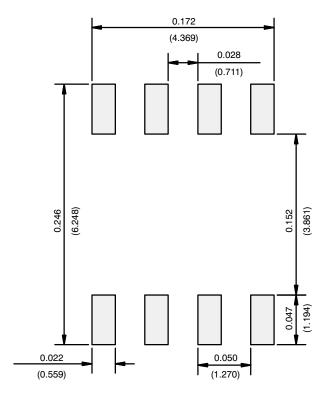


	MILLIMETERS		INC	HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A <sub>1</sub>	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498



### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)



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